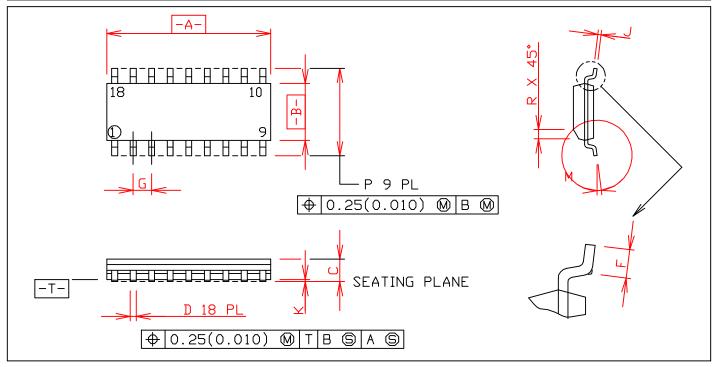
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DIM	MILLIMETERS MIN MAX		INC MIN	HES MAX
ABCDFGJKMPR	11.40 7.40 2.35 0.35 0.50 1.25 0.10 0° 10.05 0.25	11.70 7.60 2.65 0.49 0.90 7 BSC 0.32 0.25 7° 10.55 0.75	0.449 0.292 0.093 0.014 0.020 0.010 0.004 0° 0.395 0.010	0.460 0.299 0.104 0.019 0.035 50 BSC 0.012 0.009 7° 0.415 0.029

CASE NO.	751C-04
SUTATS	MS-013AB
NEW STD	X, TA
USED ON	18 LD W/B SOIC

## NOTES:

- 1. DIMENSIONS "A " AND "B" ARE DATUMS AND "T" IS A DATUM SURFACE.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982
- 3. CONTROLLING DIMENSION: MILLIMETER
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- 5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 6. 751C-01 THRU -03 DBSDLETE, NEW STANDARD 751C-04.
- 7. DIMENSION "D" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE "D" DIMENSION AT MAXIMUM MATERIAL CONDITION.

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ISSUE	REVISION	COORD/ DATE
F	Revision to change legal ownership of document from Motorola to	FB
	ON Semiconductor. Requested by Frank Padilla.	29 Sept 2000